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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 12x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UQFN Exposed Pad
Supplier Device Package	28-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep16gs502t-i-2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (VIH) and Voltage Input Low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB[®] PICkit[™] 3, MPLAB ICD 3, or MPLAB REAL ICE[™].

For more information on MPLAB ICD 2, MPLAB ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- "Using MPLAB[®] ICD 3" (poster) DS51765
- "Multi-Tool Design Advisory" DS51764
- "MPLAB[®] REAL ICE[™] In-Circuit Emulator User's Guide" DS51616
- "Using MPLAB[®] REAL ICE™ In-Circuit Emulator" (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For details, see **Section 8.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.



SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EP64GS50X DEVICES (DUAL PARTITION) 0x000000 GOTO Instruction 0x000002 Reset Address 0x000004 Interrupt Vector Table 0x0001FE 0x000200 Active Program Flash Memory (10,944 instructions) **Active Partition** 0x00577E 0x005780 **Device Configuration** 0x0057FE 0x005800 User Memory Space Unimplemented (Read '0's) 0x3FFFFE 0x400000 GOTO Instruction 0x400002 Reset Address 0x400004 Interrupt Vector Table 0x4001FE 0x400200 **Inactive Partition** Inactive Program Flash Memory (10,944 instructions) 0x40577E 0x405780 **Device Configuration** 0x4057FE 0x405800 Unimplemented (Read '0's) 0x7FFFFE 0x800000 Reserved 0x800E46 0x800E48 Calibration Data 0x800E78 0x800E7A Reserved 0x800EFE Configuration Memory Space 0x800F00 UDID 0x800F08 0x800F0A Reserved 0x800F7E 0x800F80 User OTP Memory 0x800FFC 0x801000 Reserved 0xF9FFFE 0xFA0000 Write Latches 0xFA0002 0xFA0004 Reserved **0xFEFFFE** 0xFF0000 DEVID 0xFF0002 0xFF0004 Reserved 0xFFFFFE Note: Memory areas are not shown to scale.

TABLE 4-16: ADC REGISTER MAP (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADLVLTRGL	03D0	LVLEN15 ⁽¹⁾	LVLEN14	LVLEN13 ⁽¹⁾	LVLEN12 ⁽²⁾	LVLEN11 ⁽²⁾	LVLEN10 ⁽²⁾	LVLEN9 ⁽²⁾	LVLEN8 ⁽²⁾	LVLEN7	LVLEN6	LVLEN5	LVLEN4	LVLEN3	LVLEN2	LVLEN1	LVLEN0	0000
ADLVLTRGH	03D2	_	_	_	_	_	_	_	_	_	_	LVLEN21	LVLEN20	LVLEN19	LVLEN18	LVLEN17 ⁽²⁾	LVLEN16 ⁽¹⁾	0000
ADCORE0L	03D4	—											0000					
ADCORE0H	03D6	_	-	-	EISEL2	EISEL1	EISEL0	RES1	RES0	_	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE1L	03D8	_	_	_	_	_	_					SAMO	C<9:0>					0000
ADCORE1H	03DA	_	-	-	EISEL2	EISEL1	EISEL0	RES1	RES0	_	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE2L	03DC	_			_							SAMO	C<9:0>					0000
ADCORE2H	03DE	—	-	-	EISEL2	EISEL1	EISEL0	RES1	RES0	—	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE3L	03E0	_	-	-	—	-	_					SAMO	C<9:0>					0000
ADCORE3H	03E2	_	-	-	EISEL2	EISEL1	EISEL0	RES1	RES0	_	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADEIEL	03F0	EIEN15 ⁽¹⁾	EIEN14 ⁽²⁾	EIEN13 ⁽¹⁾	EIEN12 ⁽²⁾	EIEN11 ⁽²⁾	EIEN10 ⁽²⁾	EIEN9 ⁽²⁾	EIEN8 ⁽²⁾	EIEN7	EIEN6	EIEN5	EIEN4	EIEN3	EIEN2	EIEN1	EIEN0	0000
ADEIEH	03F2	_	-	-	—	-	_	_	_	_	_	EIEN21	EIEN20	EIEN19	EIEN18	EIEN17 ⁽²⁾	EIEN16 ⁽¹⁾	0000
ADEISTATL	03F8	EISTAT15 ⁽¹⁾	EISTAT14 ⁽²⁾	EISTAT13 ⁽¹⁾	EISTAT12(2)	EISTAT11 ⁽²⁾	EISTAT10 ⁽²⁾	EISTAT9 ⁽²⁾	EISTAT8 ⁽²⁾	EISTAT7	EISTAT6	EISTAT5	EISTAT4	EISTAT3	EISTAT2	EISTAT1	EISTAT0	0000
ADEISTATH	03FA	—	_	-	—	_	_	_	_	—	—	EISTAT21	EISTAT20	EISTAT19	EISTAT18	EISTAT17 ⁽²⁾	EISTAT16 ⁽¹⁾	0000
ADCON5L	0400	SHRRDY	-	-	—	C3RDY	C2RDY	C1RDY	CORDY	SHRPWR	_	_	_	C3PWR	C2PWR	C1PWR	C0PWR	0000
ADCON5H	0402	—	-	-	—	WARMTIME3	WARMTIME2	WARMTIME1	WARMTIME0	SHRCIE	_	_	_	C3CIE	C2CIE	C1CIE	C0CIE	0000
ADCAL0L	0404	CAL1RDY	_	_	_	_	CAL1DIFF	CAL1EN	CAL1RUN	CALORDY	_	_	_	_	CAL0DIFF	CAL0EN	CALORUN	0000
ADCAL0H	0406	CAL3RDY	-	-	—	-	CAL3DIFF	CAL3EN	CAL3RUN	CAL2RDY	_	_	_	_	CAL2DIFF	CAL2EN	CAL2RUN	0000
ADCAL1H	040A	CSHRRDY	_	_	_	_	CSHRDIFF	CSHREN	CSHRRUN	_	-	-	_	_	-	-	_	0000
ADCBUF0	040C								ADC Da	ta Buffer 0								0000
ADCBUF1	040E								ADC Da	ta Buffer 1								0000
ADCBUF2	0410								ADC Da	ta Buffer 2								0000
ADCBUF3	0412								ADC Da	ta Buffer 3								0000
ADCBUF4	0414								ADC Da	ta Buffer 4								0000
ADCBUF5	0416								ADC Da	ta Buffer 5								0000
ADCBUF6	041B								ADC Da	ta Buffer 6								0000
ADCBUF7	041A								ADC Da	ta Buffer 7								0000
ADCBUF8	041C								ADC Da	ta Buffer 8								0000
ADCBUF9	041E								ADC Da	ta Buffer 9								0000
ADCBUF10	0420								ADC Dat	a Buffer 10								0000
ADCBUF11	0422								ADC Dat	a Buffer 11								0000
ADCBUF12	0424								ADC Dat	a Buffer 12								0000
ADCBUF13	0426								ADC Dat	a Buffer 13								0000
ADCBUF14	0428								ADC Dat	a Buffer 14								0000
ADCBUF15	042A								ADC Dat	a Buffer 15								0000
ADCBUF16	042C								ADC Dat	a Buffer 16								0000
ADCBUF17	042E								ADC Dat	a Buffer 17								0000
ADCBUF18	0430								ADC Dat	a Buffer 18								0000
ADCBUF19	0432								ADC Dat	a Buffer 19								0000
ADCBUF20	0434								ADC Dat	a Buffer 20								0000
ADCBUF21	0436								ADC Dat	a Buffer 21								0000

dsPIC33EPXXGS50X FAMILY

- = unimplemented, read as '0'. Reset values are shown in hexadecimal. Legend:

Note 1:

Implemented on dsPIC33EPXXGS506 devices only.
 Implemented on dsPIC33EPXXGS504/505 and dsPIC33EPXXGS506 devices only.

4.5.1 PAGED MEMORY SCHEME

The dsPIC33EPXXGS50X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre- and post-modified Effective Addresses (EAs). The upper half of the base Data Space address is used in conjunction with the Data Space Page (DSRPAG) register to form the Program Space Visibility (PSV) address.

The Data Space Page (DSRPAG) register is located in the SFR space. Construction of the PSV address is shown in Figure 4-9. When DSRPAG<9> = 1 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit PSV read address. The paged memory scheme provides access to multiple 32-Kbyte windows in the PSV memory. The Data Space Page (DSRPAG) register, in combination with the upper half of the Data Space address, can provide up to 8 Mbytes of PSV address space. The paged data memory space is shown in Figure 4-10.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG.

FIGURE 4-9: PROGRAM SPACE VISIBILITY (PSV) READ ADDRESS GENERATION



When a PSV page overflow or underflow occurs, EA<15> is cleared as a result of the register indirect EA calculation. An overflow or underflow of the EA in the PSV pages can occur at the page boundaries when:

- The initial address, prior to modification, addresses the PSV page
- The EA calculation uses Pre- or Post-Modified Register Indirect Addressing; however, this does not include Register Offset Addressing

In general, when an overflow is detected, the DSRPAG register is incremented and the EA<15> bit is set to keep the base address within the PSV window. When an underflow is detected, the DSRPAG register is decremented and the EA<15> bit is set to keep the base

address within the PSV window. This creates a linear PSV address space, but only when using Register Indirect Addressing modes.

Exceptions to the operation described above arise when entering and exiting the boundaries of Page 0 and PSV spaces. Table 4-37 lists the effects of overflow and underflow scenarios at different boundaries.

In the following cases, when overflow or underflow occurs, the EA<15> bit is set and the DSRPAG is not modified; therefore, the EA will wrap to the beginning of the current page:

- Register Indirect with Register Offset Addressing
- Modulo Addressing
- Bit-Reversed Addressing

TABLE 4-37:	OVERFLOW AND UNDERFLOW SCENARIOS AT PAGE 0 AND
	PSV SPACE BOUNDARIES ^(2,3,4)

0/11	Operation		Before		After			
0/0, R/W		DSxPAG	DS EA<15>	Page Description	DSxPAG	DS EA<15>	Page Description	
O, Read	[++\Wn]	DSRPAG = 0x2FF	1	PSV: Last lsw page	DSRPAG = 0x300	1	PSV: First MSB page	
O, Read	[Wn++]	DSRPAG = 0x3FF	1	PSV: Last MSB page	DSRPAG = 0x3FF	0	See Note 1	
U, Read		DSRPAG = 0x001	1	PSV page	DSRPAG = 0x001	0	See Note 1	
U, Read	[Wn] Or [Wn]	DSRPAG = 0x200	1	PSV: First Isw page	DSRPAG = 0x200	0	See Note 1	
U, Read		DSRPAG = 0x300	1	PSV: First MSB page	DSRPAG = 0x2FF	1	PSV: Last lsw page	

Legend: O = Overflow, U = Underflow, R = Read, W = Write

Note 1: The Register Indirect Addressing now addresses a location in the base Data Space (0x0000-0x7FFF).

2: An EDS access, with DSRPAG = 0x000, will generate an address error trap.

3: Only reads from PS are supported using DSRPAG.

4: Pseudolinear Addressing is not supported for large offsets.

4.5.2 EXTENDED X DATA SPACE

The lower portion of the base address space range, between 0x0000 and 0x7FFF, is always accessible, regardless of the contents of the Data Space Page register. It is indirectly addressable through the register indirect instructions. It can be regarded as being located in the default EDS Page 0 (i.e., EDS address range of 0x000000 to 0x007FFF with the base address bit, EA<15> = 0, for this address range). However, Page 0 cannot be accessed through the upper 32 Kbytes, 0x8000 to 0xFFFF, of base Data Space in combination with DSRPAG = 0x00. Consequently, DSRPAG is initialized to 0x001 at Reset.

- Note 1: DSRPAG should not be used to access Page 0. An EDS access with DSRPAG set to 0x000 will generate an address error trap.
 - 2: Clearing the DSRPAG in software has no effect.

The remaining PSV pages are only accessible using the DSRPAG register in combination with the upper 32 Kbytes, 0x8000 to 0xFFFF, of the base address, where base address bit, EA<15> = 1.

4.5.3 SOFTWARE STACK

The W15 register serves as a dedicated Software Stack Pointer (SSP), and is automatically modified by exception processing, subroutine calls and returns; however, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies reading, writing and manipulating the Stack Pointer (for example, creating stack frames).

Note:	To protect against misaligned stack
	accesses, W15<0> is fixed to '0' by the
	hardware.

W15 is initialized to 0x1000 during all Resets. This address ensures that the SSP points to valid RAM in all dsPIC33EPXXGS50X devices and permits stack availability for non-maskable trap exceptions. These can occur before the SSP is initialized by the user software. You can reprogram the SSP during initialization to any location within Data Space.

The Software Stack Pointer always points to the first available free word and fills the software stack, working from lower toward higher addresses. Figure 4-11 illustrates how it pre-decrements for a stack pop (read) and post-increments for a stack push (writes). When the PC is pushed onto the stack, PC<15:0> are pushed onto the first available stack word, then PC<22:16> are pushed into the second available stack location. For a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, as shown in Figure 4-11. During exception processing, the MSB of the PC is concatenated with the lower 8 bits of the CPU STATUS Register, SR. This allows the contents of SRL to be preserved automatically during interrupt processing.

- **Note 1:** To maintain system Stack Pointer (W15) coherency, W15 is never subject to (EDS) paging, and is therefore, restricted to an address range of 0x0000 to 0xFFFF. The same applies to the W14 when used as a Stack Frame Pointer (SFA = 1).
 - 2: As the stack can be placed in, and can access X and Y spaces, care must be taken regarding its use, particularly with regard to local automatic variables in a C development environment

FIGURE 4-11: CALL STACK FRAME



REGISTER 5-1: NVMCON: NONVOLATILE MEMORY (NVM) CONTROL REGISTER

R/SO-0	⁽¹⁾ R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0	R/C-0	R-0	R/W-0	R/C-0
WR	WREN	WRERR	NVMSIDL ⁽²⁾	SFTSWP ⁽⁶⁾	P2ACTIV ⁽⁶⁾	RPDF	URERR
bit 15		•	•		-	•	bit 8
U-0	U-0	U-0	U-0	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾	R/W-0 ⁽¹⁾
_			—	NVMOP3 ^(3,4)	NVMOP2 ^(3,4)	NVMOP1 ^(3,4)	NVMOP0 ^(3,4)
bit 7							bit 0
Legend:		C = Clearab	le bit	SO = Settable	Only bit		
R = Read	able bit	W = Writable	e bit	U = Unimplem	ented bit, read	as '0'	
-n = Value	at POR	'1' = Bit is se	et	'0' = Bit is clea	ired	x = Bit is unkr	iown
		(4)					
bit 15	WR: Write Co	ontrol bit()					
	1 = Initiates a cleared b	a ⊢lash mem ov hardware c	ory program o	r erase operati	on; the operation	on is self-timed	and the bit is
	0 = Program	or erase ope	ration is compl	ete and inactive	e		
bit 14	WREN: Write	Enable bit ⁽¹⁾					
	1 = Enables	Flash prograi	m/erase operat	ions			
	0 = Inhibits F	lash program	n/erase operatio	ons			
bit 13	WRERR: Writ	te Sequence	Error Flag bit()			
	1 = An improj	per program c	or erase sequen	ce attempt, or te	ermination has o	ccurred (bit is se	et automatically
	0 = The prog	ram or erase	operation com	pleted normally	/		
bit 12	NVMSIDL: N	VM Stop in Id	lle Control bit ⁽²⁾)			
	1 = Flash vol	tage regulato	or goes into Sta	ndby mode dur	ing Idle mode		
	0 = Flash vol	tage regulato	or is active durin	ng Idle mode			
bit 11	SFTSWP: Pa	rtition Soft Sv	wap Status bit ^{(c}	») 			
	1 = Partitions	s have been s	successfully sw artition swap us	apped using th	e BOOTSWP inst	truction (soft sw	/ap) t will determine
	the Active	e Partition ba	sed on FBTSE				
bit 10	P2ACTIV: Pa	rtition 2 Activ	e Status bit ⁽⁶⁾				
	1 = Partition	2 Flash is ma	apped into the a	active region			
	0 = Partition	1 Flash is ma	apped into the a	active region			
bit 9	RPDF: Row F	Programming	Data Format b	oit .			
	\perp = Row data 0 = Row data	a to be stored a to be stored	in RAM in con	ompressed forma	nat		
Note 1:	These bits can on	ly be reset or	n a POR.				1
2:	delay (TVREG) bef	ore Flash me	morv becomes	operational.	DLE) and upon (exiting late mod	le, there is a
3:	All other combinat	ions of NVM	OP<3:0> are ur	nimplemented.			
4:	Execution of the P	WRSAV instru	ction is ignored	d while any of th	ne NVM operati	ons are in prog	ress.
5:	Two adjacent word	ds on a 4-wor	rd boundary are	e programmed	during executio	n of this operat	ion.
6:	Only available on	dsPIC33EP6	4GS50X device	es operating in	Dual Partition r	node. For all ot	her devices,
7.	The specific Root	ı. mode denen:	ds on hite<1.05	of the program	med data.		
	11 = Single Partiti	on Flash mod	de	or the program			
	10 = Dual Partition	n Flash mode)				
	01 = Protected Du	ual Partition F	lash mode				

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1 (CONTINUED)

- bit 2
 STKERR: Stack Error Trap Status bit

 1 = Stack error trap has occurred
 0 = Stack error trap has not occurred

 bit 1
 OSCFAIL: Oscillator Failure Trap Status bit

 1 = Oscillator failure trap has occurred
 0 = Oscillator failure trap has not occurred
- bit 0 Unimplemented: Read as '0'

8.5 Oscillator Control Registers

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER⁽¹⁾

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
	COSC2	COSC1	COSC0	—	NOSC2 ⁽²⁾	NOSC1 ⁽²⁾	NOSC0 ⁽²⁾
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/W-0	U-0	U-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF ⁽³⁾	—	—	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR						
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'					
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown				

bit 15	Unimplemented: Read as '0'
bit 14-12	COSC<2:0>: Current Oscillator Selection bits (read-only) 111 = Fast RC Oscillator (FRC) with Divide-by-n 110 = Fast RC Oscillator (FRC) with Divide-by-16 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved 011 = Primary Oscillator (XT, HS, EC) with PLL 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL) 000 = Fast RC Oscillator (FRC)
bit 11	Unimplemented: Read as '0'
bit 10-8	NOSC<2:0>: New Oscillator Selection bits ⁽²⁾
	 111 = Fast RC Oscillator (FRC) with Divide-by-n 110 = Fast RC Oscillator (FRC) with Divide-by-16 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved
	011 = Primary Oscillator (XT, HS, EC) with PLL 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL) 000 = Fast RC Oscillator (FRC)
bit 7	CLKLOCK: Clock Lock Enable bit
	 1 = If (FCKSM0 = 1), then clock and PLL configurations are locked; if (FCKSM0 = 0), then clock and PLL configurations may be modified 0 = Clock and PL selections are not locked, configurations may be modified
bit 6	IOLOCK: I/O Lock Enable bit
2	1 = I/O lock is active 0 = I/O lock is not active
bit 5	LOCK: PLL Lock Status bit (read-only)
	 1 = Indicates that PLL is in lock or PLL start-up timer is satisfied 0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled
Note 1:	Writes to this register require an unlock sequence.
2:	Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.
э.	This bit should only be cleared in software. Softing the bit in software (-1) will have the same affect as an

3: This bit should only be cleared in software. Setting the bit in software (= 1) will have the same effect as an actual oscillator failure and will trigger an oscillator failure trap.

NOTES:

REGISTER 14-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2 (CONTINUED)

- bit 4-0 SYNCSEL<4:0>: Trigger/Synchronization Source Selection bits
 - 11111 = OCxRS compare event is used for synchronization
 - 11110 = INT2 pin synchronizes or triggers OCx
 - 11101 = INT1 pin synchronizes or triggers OCx
 - 11100 = Reserved
 - 11011 = CMP4 module synchronizes or triggers OCx
 - 11010 = CMP3 module synchronizes or triggers OCx
 - 11001 = CMP2 module synchronizes or triggers OCx
 - 11000 = CMP1 module synchronizes or triggers OCx
 - 10111 = Reserved
 - 10110 = Reserved
 - 10101 = Reserved
 - 10100 = Reserved
 - 10011 = IC4 input capture interrupt event synchronizes or triggers OCx
 - 10010 = IC3 input capture interrupt event synchronizes or triggers OCx
 - 10001 = IC2 input capture interrupt event synchronizes or triggers OCx
 - 10000 = IC1 input capture interrupt event synchronizes or triggers OCx
 - 01111 = Timer5 synchronizes or triggers OCx
 - 01110 = Timer4 synchronizes or triggers OCx
 - 01101 = Timer3 synchronizes or triggers OCx
 - 01100 = Timer2 synchronizes or triggers OCx (default)
 - 01011 = Timer1 synchronizes or triggers OCx
 - 01010 = Reserved
 - 01001 = Reserved
 - 01000 = IC4 input capture event synchronizes or triggers OCx
 - 00111 = IC3 input capture event synchronizes or triggers OCx
 - 00110 = IC2 input capture event synchronizes or triggers OCx
 - 00101 = IC1 input capture event synchronizes or triggers OCx
 - 00100 = OC4 module synchronizes or triggers $OCx^{(1,2)}$
 - 00011 = OC3 module synchronizes or triggers $OCx^{(1,2)}$
 - 00010 = OC2 module synchronizes or triggers $OCx^{(1,2)}$
 - 00001 = OC1 module synchronizes or triggers $OCx^{(1,2)}$
 - 00000 = No sync or trigger source for OCx
- Note 1: Do not use the OCx module as its own synchronization or trigger source.
 - 2: When the OCy module is turned off, it sends a trigger out signal. If the OCx module uses the OCy module as a trigger source, the OCy module must be unselected as a trigger source prior to disabling it.

REGISTER 15-5: STCON: PWMx SECONDARY MASTER TIME BASE CONTROL REGISTER

		_				_				
U-0	U-0	U-0	R-0, HSC	R/W-0	R/W-0	R/W-0	R/W-0			
	_	_	SESTAT	SEIEN	EIPU ⁽¹⁾	SYNCPOL	SYNCOEN			
bit 15							bit 8			
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
SYNCEN	SYNCSRC2	SYNCSRC1	SYNCSRC0	SEVTPS3	SEVTPS2	SEVTPS1	SEVTPS0			
bit 7		bit C								
Legend:		HSC = Hardw	are Settable/Cl	earable bit						
R = Readable	bit	W = Writable	oit	U = Unimplen	nented bit, read	d as '0'				
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkn	iown			
bit 15-13	Unimplement	ted: Read as 'd)'							
bit 12	SESTAT: Spec	cial Event Inter	rupt Status bit							
	1 = Secondary	y special event	interrupt is per	nding						
	0 = Secondary	y special event	interrupt is not	pending						
bit 11	SEIEN: Specia	al Event Interru	ipt Enable bit							
	1 = Secondary	y special event	interrupt is ena	abled						
h# 40		y special event								
UF JIG		immediate Pel	rogistor is und	n''	olv					
	1 - Active Sec0 = Active Sec	condary Period	register update	es occur on PV	VMx cycle bou	ndaries				
bit 9	SYNCPOL: S	ynchronize Inp	ut and Output F	Polarity bit						
	1 = SYNCIx/S 0 = SYNCIx/S	YNCO2 polarit	y is inverted (a y is active-high	ctive-low)						
bit 8	SYNCOEN: S	econdary Mast	ter Time Base S	Synchronizatio	n Enable bit					
	1 = SYNCO2 0 = SYNCO2	output is enabl output is disab	ed led							
bit 7	SYNCEN: Ext	ernal Seconda	ry Master Time	Base Synchro	onization Enabl	e bit				
	1 = External s 0 = External s	ynchronization	of secondary t	ime base is en ime base is dis	abled					
bit 6-4	SYNCSRC<2	:0>: Secondary	/ Time Base Sv	nc Source Sel	ection bits					
	111 = Reserv	ed								
	101 = Reserv	ed								
	100 = Reserv	ed								
	010 = Reserv	ed ed								
	001 = SYNCI2	2								
	000 = SYNCI	1								
bit 3-0	SEVTPS<3:0:	>: PWMx Seco	ndary Special E	Event Trigger (Output Postsca	ler Select bits				
	1111 = 1:16 F	Postcale								
	•	osicale								
	•									
	•									
	0000 = 1:1 Pc	ostscale								

Note 1: This bit only applies to the secondary master time base period.

x = Bit is unknown

REGISTER 15-6: STCON2: PWMx SECONDARY CLOCK DIVIDER SELECT REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	_
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	P	CLKDIV<2:0>(1)
bit 7							bit 0
Legend:							
R = Readable bit W = Writable bit			U = Unimplem	ented bit, read	as '0'		

'0' = Bit is cleared

bit 15-3 Unimplemented: Read as '0'

-n = Value at POR

bit 2-0

PCLKDIV<2:0>: PWMx Input Clock Prescaler (Divider) Select bits⁽¹⁾

111 = Reserved

110 = Divide-by-64, maximum PWM timing resolution

'1' = Bit is set

101 = Divide-by-32, maximum PWM timing resolution

100 = Divide-by-16, maximum PWM timing resolution

- 011 = Divide-by-8, maximum PWM timing resolution
- 010 = Divide-by-4, maximum PWM timing resolution
- 001 = Divide-by-2, maximum PWM timing resolution

000 = Divide-by-1, maximum PWM timing resolution (power-on default)

Note 1: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 15-7: STPER: PWMx SECONDARY MASTER TIME BASE PERIOD REGISTER^(1,2)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
			STPE	R<15:8>			
bit 15							bit 8
R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
			STP	ER<7:0>			
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable bi	it	U = Unimplen	nented bit, rea	ad as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkr	nown

bit 15-0 STPER<15:0>: Secondary Master Time Base (SMTMR) Period Value bits

Note 1: The PWMx time base has a minimum value of 0x0010 and a maximum value of 0xFFF8.

2: Any period value that is less than 0x0028 must have the Least Significant 3 bits set to '0', thus yielding a period resolution at 8.32 ns (at fastest auxiliary clock rate).

REGISTER 20-2: CMPxDAC: COMPARATOR x DAC CONTROL REGISTER

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0		
			_		CMREF	-<11:8>			
bit 15							bit 8		
R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
			CMRE	F<7:0>					
bit 7							bit 0		
Legend:									
R = Readable	bit	W = Writable I	oit	U = Unimplemented bit, read as '0'					
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unknown			
							,		
bit 15-12	Unimplemen	ted: Read as 'o)'						
bit 11-0	CMREF<11:0	>: Comparator	Reference Vo	oltage Select b	its				
	11111111111	11		-					
	•								
	•								
	•	= ([CMREF<11:0>] * (AVDD)/4096) volts (EXTREF = 0)							
	•	or ([CMRI	EF<11:0>] * (EXTREF)/409	6) volts (EXTRE	EF = 1)			
	•								
	•								
	0000000000	00							

TABLE 23-1: CONFIGURATION REGISTER MAP⁽³⁾ (CONTINUED)

Name	Address	Device Memory Size (Kbytes)	Bits 23-16	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FDEVOPT	002BAC	16																	
	0057AC	32	_	_	_	_	_	_	_	_	_	_	DBCC	_	ALTI2C2	ALTI2C1	Reserved ⁽¹⁾	_	PWMLOCH
	00AFAC	64																	
FALTREG	002BB0	16																	
	0057B0	32	_	_	_	_	_	_	_	_	_	-		CTXT2<2:	0>	—	c	CTXT1<2:0	>
	00AFB0	64																	
FBTSEQ	002BFC	16									•								
	0057FC	32		IBSE	EQ<11:0>								I	BSEQ<11:0	>				
	00AFFC	64																	
FBOOT ⁽⁴⁾	801000	—	_	_		_	_	_		_	_	_	—		_	_	_	BTMC	DDE<1:0>

Note 1: These bits are reserved and must be programmed as '1'.

2: This bit is reserved and must be programmed as '0'.

3: When operating in Dual Partition mode, each partition will have dedicated Configuration registers. On a device Reset, the configuration values of the Active Partition are read at start-up, but during a soft swap condition, the configuration settings of the newly Active Partition are ignored.

4: FBOOT resides in configuration memory space.

Bit Field	Description
FNOSC<2:0>	Oscillator Selection bits
	111 = Fast RC Oscillator with Divide-by-N (FRCDIVN)
	110 = Fast RC Oscillator with Divide-by-16
	101 = Low-Power RC Oscillator (LPRC)
	100 = Reserved; do not use
	011 = Primary Oscillator With PLL module (XTPLL, HSPLL, ECPLL)
	010 = Filling Oscillator with Divide by N with PLL module (FRCPLL)
	000 = Fast RC Oscillator (FRC)
FCKSM<1:0>	Clock Switching Mode bits
	1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
	01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
	00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	Peripheral Pin Select Configuration bit
	1 = Allows only one reconfiguration
	0 = Allows multiple reconfigurations
OSCIOFNC	OSC2 Pin Function bit (except in XT and HS modes)
	1 = OSC2 is the clock output
	0 = OSC2 is a general purpose digital I/O pin
POSCMD<1:0>	Primary Oscillator Mode Select bits
	11 = Primary Oscillator is disabled
	10 = HS Crystal Oscillator mode
	01 = XT Crystal Oscillator mode
WDTEN<1:0>	Watchdog Timer Enable bits
	SWDTEN bit in the RCON register will have no effect)
	10 = Watchdog Timer is enabled/disabled by user software (I PRC can be disabled by
	clearing the SWDTEN bit in the RCON register)
	01 = Watchdog Timer is enabled only while device is active and is disabled while in Sleep
	mode; software control is disabled in this mode
	00 = Watchdog Timer and SWDTEN bit are disabled
WINDIS	Watchdog Timer Window Enable bit
	1 = Watchdog Timer in Non-Window mode
	0 = Watchdog Timer in Window mode
PLLKEN	PLL Lock Enable bit
	1 = PLL lock is enabled
	0 = PLL lock is disabled
WDTPRE	Watchdog Timer Prescaler bit
	1 = 1:128
	0 = 1:32
WDTPOST<3:0>	Watchdog Timer Postscaler bits
	1111 = 1:32,768
	1110 = 1:16,384
	•
	•
	0001 = 1:2
	0000 = 1:1

TABLE 23-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Note 1: The Boot Segment must be present to use the Alternate Interrupt Vector Table.

26.1 DC Characteristics

TABLE 26-1: OPERATING MIPS vs. VOLTAGE

Charactoristic	VDD Range	Temperature Range	Maximum MIPS		
Characteristic	(in Volts)	(in °C)	dsPIC33EPXXGS50X Family		
	3.0V to 3.6V ⁽¹⁾	-40°C to +85°C	70		
_	3.0V to 3.6V ⁽¹⁾	-40°C to +125°C	60		

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, PGAs and comparators) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 26-13 for the minimum and maximum BOR values.

TABLE 26-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Тур.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal Chip Power Dissipation: $PINT = VDD x (IDD - \Sigma IOH)$ I/O Pin Power Dissipation: $I/O = \Sigma (I/VDD - VOH) x IOH) + \Sigma (VOL x IOL)$	PD	Pint + Pi/o		W	
Maximum Allowed Power Dissipation	PDMAX	(TJ – TΑ)/θJΑ			W

TABLE 26-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Тур.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin TQFP 10x10x1 mm	θJA	49.0		°C/W	1
Package Thermal Resistance, 48-Pin TQFP 7x7x1.0 mm	θJA	63.0	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN 8x8 mm	θJA	29.0	—	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10x1 mm	θJA	50.0	—	°C/W	1
Package Thermal Resistance, 28-Pin QFN-S 6x6x0.9 mm	θJA	30.0	—	°C/W	1
Package Thermal Resistance, 28-Pin UQFN 6x6x0.5 mm	θJA	26.0	—	°C/W	1
Package Thermal Resistance, 28-Pin SOIC 7.50 mm	θJA	70.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ JA) numbers are achieved by package simulations.

- (1)



TABLE 26-24:	TIMER1 EXTERNAL CLOCK	

AC CHARACTERISTICS				$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^\circ C \leq TA \leq +85^\circ C \mbox{ for Industrial} \\ & -40^\circ C \leq TA \leq +125^\circ C \mbox{ for Extended} \end{array}$					
Param No.	Symbol	Characteristic ⁽²⁾		Min.	Тур.	Max.	Units	Conditions	
TA10	T⊤xH	T1CK High Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N		_	ns	Must also meet Parameter TA15, N = Prescale Value (1, 8, 64, 256)	
			Asynchronous	35	—	—	ns		
TA11	ΤτxL	T1CK Low Time	Synchronous mode	Greater of: 20 or (Tcy + 20)/N	_	_	ns	Must also meet Parameter TA15, N = Prescale Value (1, 8, 64, 256)	
			Asynchronous	10	_	—	ns		
TA15	ΤτχΡ	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 Tcy + 40)/N	_	_	ns	N = Prescale Value (1, 8, 64, 256)	
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting bit, TCS (T1CON<1>))		DC	_	50	kHz		
TA20	TCKEXTMRL	Delay from E Clock Edge t Increment	xternal T1CK o Timer	0.75 Tcy + 40		1.75 Tcy + 40	ns		

Note 1: Timer1 is a Type A timer.

2: These parameters are characterized but not tested in manufacturing.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

Microchip Tradema Architecture — Flash Memory Fam Program Memory S Product Group — Pin Count — Tape and Reel Flag Temperature Range Package Pattern	dsPIC 33 EP 64 GS5 04 T - 1 / PT XXX rk	Examples: dsPIC33EP64GS504-I/PT: dsPIC33, Enhanced Performance, 64-Kbyte Program Memory, SMPS, 44-Pin, Industrial Temperature, TQFP Package.
Architecture:	33 = 16-Bit Digital Signal Controller	
Flash Memory Family:	EP = Enhanced Performance	
Product Group:	GS = SMPS Family	
Pin Count:	02 = 28-pin 04 = 44-pin 05 = 48-pin 06 = 64-pin	
Temperature Range:	$ \begin{array}{rcl} I &=& -40^{\circ} C \text{ to } +85^{\circ} C \text{ (Industrial)} \\ E &=& -40^{\circ} C \text{ to } +125^{\circ} C \text{ (Extended)} \end{array} $	
Package:	2N=Ultra Thin Quad Flat, No Lead - (28-pin) 6x6 mm (UQFN)ML=Plastic Quad Flat, No Lead - (44-pin) 8x8 mm body (QFN)MM=Plastic Quad Flat, No Lead - (28-pin) 6x6 mm body (QFN-S)PT=Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)PT=Plastic Thin Quad Flatpack - (64-pin) 10x10 mm body (TQFP)SO=Plastic Small Outline, Wide - (28-pin) 7.50 mm body (SOIC)Y8=Thin Quad Flatpack - (48-pin) 7x7 mm (TQFP)	